

USB 2.0 Connectors

Description:

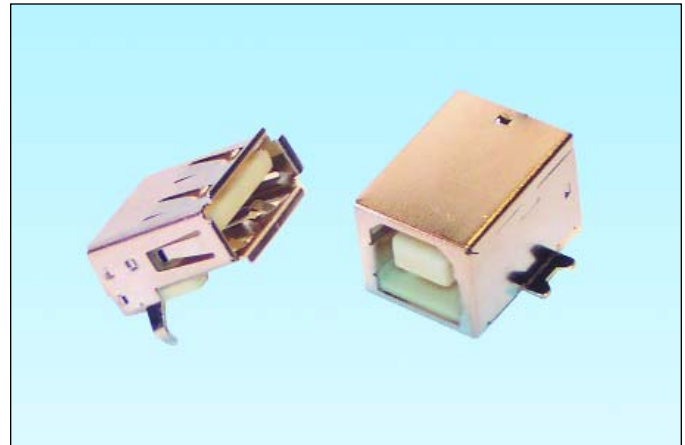
Board mount I/O connectors for the industry standard USB (Universal Serial Bus) interface used to connect peripheral devices to computers. USB 2.0 is backwards compatible with today's products, while also meeting the electrical requirements for higher speed USB 2.0 peripherals.

Typical Applications:

- Desktop and notebook computers
- Portable music recorders/players
- Printers and scanners
- External disk drives

Benefits/Features:

- Industry Standard Meets the speed requirements of USB 2.0. Compatible with USB 1.1 devices.
- Flexible System Operates at 1.5 Mb/s, 12 Mb/s, and 480 Mb/s. Through hole and SMT mounting styles are available. Allows for hot plugging of multiple devices.
- Ruggedness and Reliability . . . Full metal shields help protect contacts from physical and ESD (Electro Static Discharge) damage. Standard product is rated for 1500 cycles.



Selectable Features:

Product Type	USB 2.0 Series "A" and "B" receptacles
Total No. of Positions	4, 8 (dual stack) 12 (triple stack)
Centerline Spacing	1.25 mm [.049 in.] 2.0 mm [.079 in.] 2.5 mm [.098 in.]
Orientation	Horizontal R/A, Vertical R/A, upright
Style	Single, double, triple
Mounting Style	Through hole or SMT
Operating Voltage	30 VAC RMS
PCB Thickness	SMT: N/A T/H: 1.57 mm [.0618 in.]
Contact Style	Formed
Contact Area Plating	Gold plated (see product print for thickness)
Shell (Shield) Material	Brass
Housing Color	Black or white

Other Properties:

Packaging Type	Tray
Housing Material	GF PBT or Nylon PA9T GF UL94V-0
Applicable Soldering Process	IR, vapor phase, wave
Contact Base Material	Phosphor bronze
Insulation Resistance	1000 MΩ initial
Withstanding Voltage	750 VAC RMS
Current Rating	1.5 amp max. per contact
Contact Resistance	30 mΩ initial
Voltage Rating	250 VAC max.
Temperature Range	-40°C to +105°C
Normal Force	30 g min. (controlled by cable connector)
Durability (Mating Cycles)	1500 cycles
Mating Force	35 N [7.9 lbf] max.
Unmating Force	10 N [2.25 lbf] min. initial
Plating (Contact Area)	Gold (thickness varies per Delphi spec.) over nickel underplating
Plating (Soldering End)	2.54 μm [100 μin.] min. tin-lead over nickel underplating
Plating (Shield)	3.048 μm [120 μin.] min. tin-lead over nickel underplating, or 2.03 μm [80 μin.] min. nickel
Underplating	1.27 μm [50 μin.] nickel
Standards	Universal Serial Bus Revision 2.0 Specification
Approvals and Certification	UL approved

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Ordering Nomenclature

1543 1483 - 1 0 0

Style A:

R/A, T/H **1543 1483**
 R/A, Double, T/H . . **1543 1484**
 R/A, SMT **1543 1485**
 Vertical, T/H **1543 1486**
 Flag, T/H **1543 1489**
 R/A, Triple, T/H . . **1543 1490**

Style B:

R/A, T/H **1543 1482**
 R/A, SMT **1543 1487**
 Vertical, T/H **1543 1488**

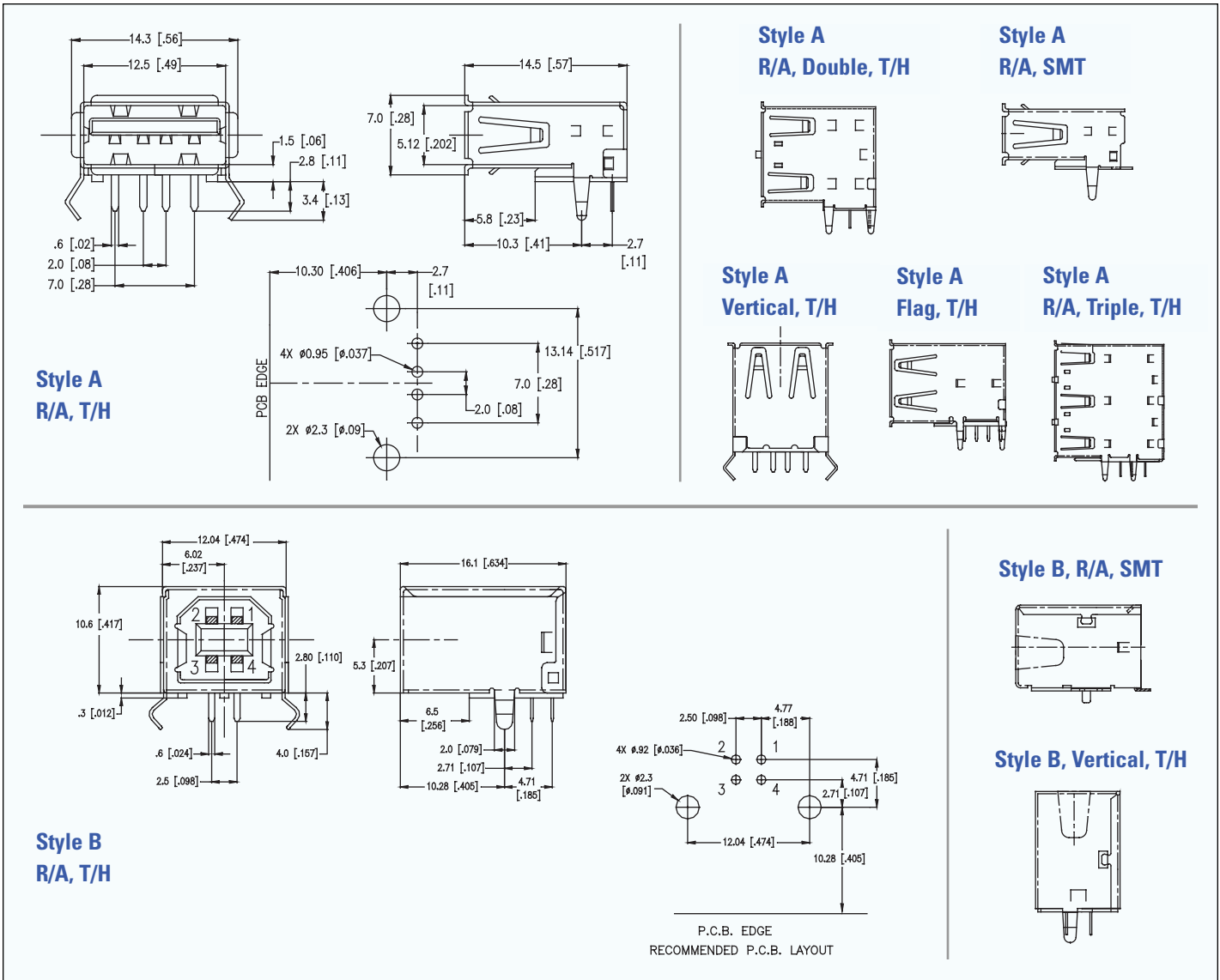
Selective Plating:

Gold plated on contact area and 2.54 µm [100 µin.] min. tin-lead plated on soldering end over 1.27 µm [50 µin.] min. nickel underplating

- 1** = Gold Flash
- 2** = 0.381 µm [15 µin.]
- 3** = 0.762 µm [30 µin.]

Housing Color:

- 0** = Black
- 1** = White



Dimensions are shown in millimeters [inches].

DELPHI

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www.delphi.com/connect

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802/3w • 1002/6mGBS • U803/3W